

**Description**

The GM76C8128A/AL/ALL is a 1,048,576 bits static random access memory organized as 131,072 words by 8 bits. Using a 0.8 $\mu$ m advanced CMOS technology, it provides high speed operation with minimum cycle time of 70/85/100ns. The device is placed in a low power standby mode with  $\overline{CS1}$  high or CS2 low and the output enable ( $\overline{OE}$ ) allows fast memory access. Thus it is suitable for high speed and low power applications, especially where battery back-up is required. The GM76C8128A/AL/ALL is offered in a 32-pin DIP (600mil), SOP (525mil) and TSOP I (0820).

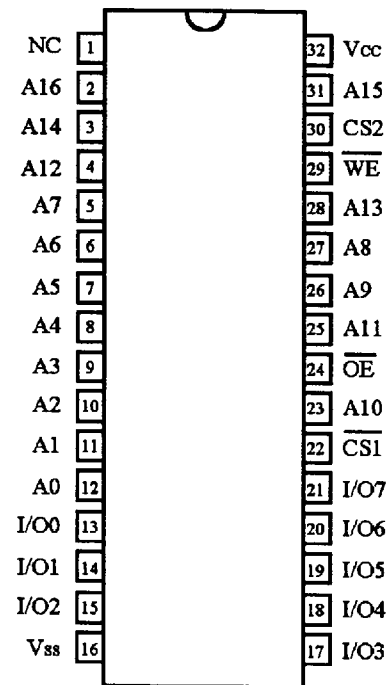
**Features**

- High Speed : Fast Access and Cycle Time  
70/85/100ns Max.
- Low Power Standby and Low Power Operation  
Standby : 5.5mW Max.  
Standby : 0.55mW Max. (L - Version)  
Standby : 0.275mW Max. (LL - Version)  
Operation : 385mW Max.
- Completely Static RAM : No Clock or Timing Strobe Required
- Equal Access and Cycle Time
- Capability of Battery Back-up Operation
- Single + 5V Operation ( $\pm 10\%$ )
- Standard 32 DIP, SOP and TSOP I

**Pin Description**

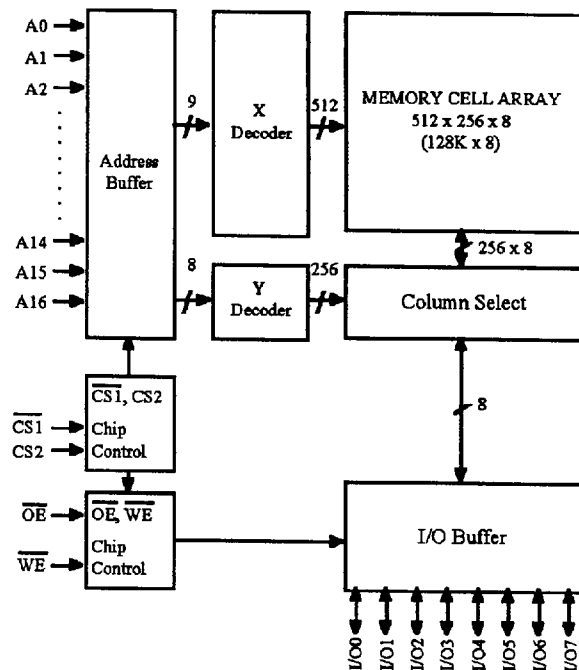
Pin	Function
A0-A16	Address Inputs
$\overline{WE}$	Write Enable Input
$\overline{CS1}$ , CS2	Chip Select Input
$\overline{OE}$	Output Enable Input
I/O0-I/O7	Data Inputs/Outputs
Vcc	Power Supply (+5V)
Vss	Ground
NC	No Connection

**Pin Configuration**



(Top View)

**Block Diagram**



**Absolute Maximum Ratings\***

Symbol	Parameter	Rating	Unit
T <sub>A</sub>	Ambient Temperature under Bias	0 ~ 70	°C
T <sub>STG</sub>	Storage Temperature	-55 ~ 150	°C
T <sub>SOL</sub>	Soldering Temperature and Time	260, 10 (at lead)	°C, S
V <sub>CC</sub>	Supply Voltage	-0.3 ~ 7.0	V
V <sub>IN</sub>	Input Voltage	-0.3* ~ 7.0	V
V <sub>IO</sub>	Input and Output Voltage	-0.5 ~ V <sub>CC</sub> + 0.5	V
P <sub>D</sub>	Power Dissipation	1.0	W

\*: -3.0V at pulse width 50ns Max.

**Recommended Operating Conditions (T<sub>A</sub> = 0 ~ 70°C)**

Symbol	Parameter	Min	Typ	Max	Unit
V <sub>CC</sub>	Supply Voltage	4.5	5.0	5.5	V
V <sub>IH</sub>	Input High Voltage	2.2	-	V <sub>CC</sub> + 0.3	V
V <sub>IL</sub>	Input Low Voltage	-0.3	-	0.8	V
V <sub>DR</sub>	Data Retention Supply Voltage	2.0	-	5.5	V

**Truth Table**

$\overline{CS1}$	CS2	$\overline{OE}$	$\overline{WE}$	A1 to A16	DATA I/O	MODE
L	H	L	H	Stable	Output Data	Read
L	H	X	L	Stable	Input Data	Write
L	H	H	H	Stable	Hi-Z	Output Disable
H	X	X	X	-	Hi-Z	Standby
X	L	X	X	-	Hi-Z	

\*Note: X means "don't care".

**DC Electrical Characteristics ( $V_{CC} = 5V \pm 10\%$ ,  $T_A = 0 \sim 70^\circ C$ )**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{I(L)}$	Input Leakage Current	$V_{IN} = 0 \text{ to } V_{CC}$	-1	-	1	$\mu A$
$I_{O(L)}$	Output Leakage Current	$\overline{CS1} = V_{IH} \text{ or } CS2 = V_{IL}$ $OE = V_{IH}, V_{SS} \leq V_{OUT} \leq V_{CC}$	-1	-	1	$\mu A$
$I_{OH}$	High Level Output Current	$V_{ON} = 2.4V$	-1.0	-	-	mA
$I_{OL}$	Low Level Output Current	$V_{ON} = 0.4V$	-	-	2.1	mA
$I_{CC}$	Operating Supply Current	$\overline{CS1} = V_{IL} \text{ or } CS2 = V_{IH}$ $V_{IN} = V_{IH}/V_{IL}, I_{OUT} = 0mA$	-	-	45	mA
$I_{CC1}$	Average Operating Current	$\overline{CS1} = V_{IL} \text{ and } CS2 = V_{IH}$ $V_{IN} = V_{IH}/V_{IL}$ $I_{OUT} = 0mA$ tcycle = Min, cycle	-	-	70	mA
$I_{CC2}$		$\overline{CS1} = 0.2V, CS2 = V_{CC}-0.2V$ $V_{IN} = V_{CC} - 0.2V/0.2V$ $I_{OUT} = 0mA$ tcycle = 1 $\mu s$	-	-	45	mA
$I_{CCS1}$	Standby Current	$\overline{CS1} = V_{IH} \text{ or } CS2 = V_{IL}$	-	-	3	mA
$I_{CCS2}$		$\overline{CS1} = V_{CC}-0.2V, CS2 = 0.2V$ GM76C8128A	-	-	1	mA
		GM76C8128AL	-	2*	100	$\mu A$
		GM76C8128ALL	-	2*	50	$\mu A$

\*TYP. Values are measured at  $25^\circ C$ ,  $V_{CC} = 5V$

**AC Operating Characteristics** ( $V_{CC} = 5V \pm 10\%$ ,  $T_A = 0 \sim 70^\circ C$ )  
**Read Cycle Cycle**

Symbol	Parameter	GM76C8128A-70		GM76C8128A-85		GM76C8128A-10		Unit
		Min	Max	Min	Max	Min	Max	
$t_{RC}$	Read Cycle Time	70	-	85	-	100	-	ns
$t_{AA}$	Address Access Time	-	70	-	85	-	100	ns
$t_{ACS1}$	Chip Select 1 Access Time	-	70	-	85	-	100	ns
$t_{ACS2}$	Chip Select 2 Access Time	-	70	-	85	-	100	ns
$t_{OE}$	Output Enable Access Time	-	35	-	45	-	50	ns
$t_{CLZ1}$	Chip Select 1 Output Setup Time	5	-	10	-	10	-	ns
$t_{CHZ1}$	Chip Select 1 Output Floating	-	25	-	30	-	35	ns
$t_{CLZ2}$	Chip Select 2 Output Setup Time	5	-	10	-	10	-	ns
$t_{CHZ2}$	Chip Select 2 Output Floating	-	25	-	30	-	35	ns
$t_{OLZ}$	Output Enable Output Setup Time	0	-	0	-	0	-	ns
$t_{OHZ}$	Output Enable Output Floating	-	25	-	30	-	35	ns
$t_{OH}$	Output Hold Time	10	-	10	-	10	-	ns

**Write Cycle**

Symbol	Parameter	GM76C8128A-70		GM76C8128A-85		GM76C8128A-10		Unit
		Min	Max	Min	Max	Min	Max	
$t_{WC}$	Write Cycle Time	70	-	85	-	100	-	ns
$t_{CW1}$	Chip Select Time 1	65	-	75	-	80	-	ns
$t_{CW2}$	Chip Select Time 2	65	-	75	-	80	-	ns
$t_{AW}$	Address Enable Time	60	-	70	-	80	-	ns
$t_{AS}$	Address Setup Time	0	-	0	-	0	-	ns
$t_{WP}$	Write Pulse Width	50	-	60	-	60	-	ns
$t_{WR}$	Address Hold Time	0	-	0	-	0	-	ns
$t_{DW}$	Input Data Setup Time	30	-	35	-	40	-	ns
$t_{DH}$	Input Data Hold Time	0	-	0	-	0	-	ns
$t_{WHZ}$	Write to Output in High-Z	-	25	-	30	-	35	ns
$t_{OW}$	Output Active from End of Write	0	-	0	-	0	-	ns

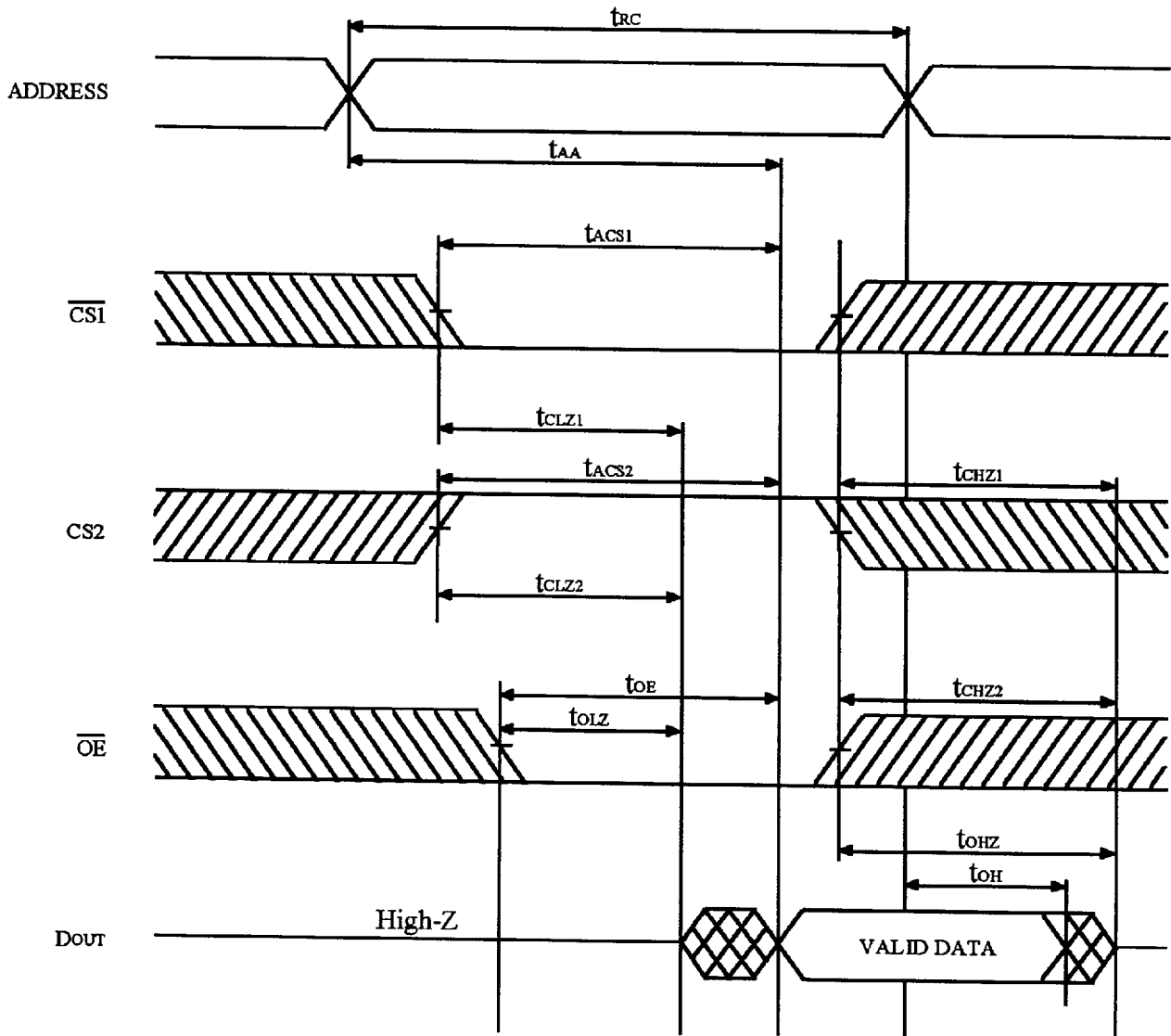
**AC TEST CONDITIONS**

- Output load : 100pF + 1TTL Gate  
 - Input pulse level : 0.6V to 2.4V

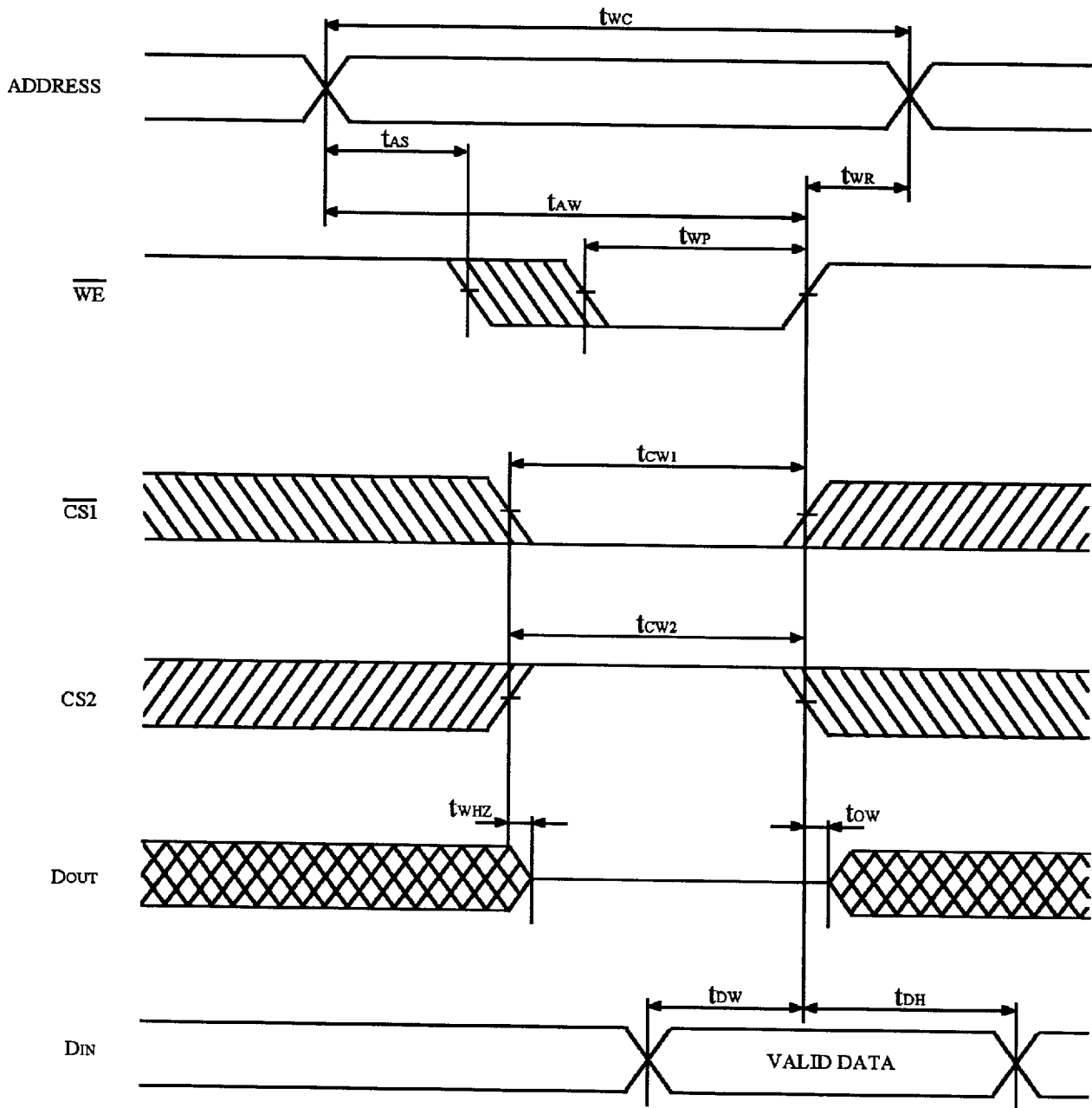
- Input and output timing reference levels : 1.5V  
 -  $t_r = t_f = 5ns$

Timing Waveforms

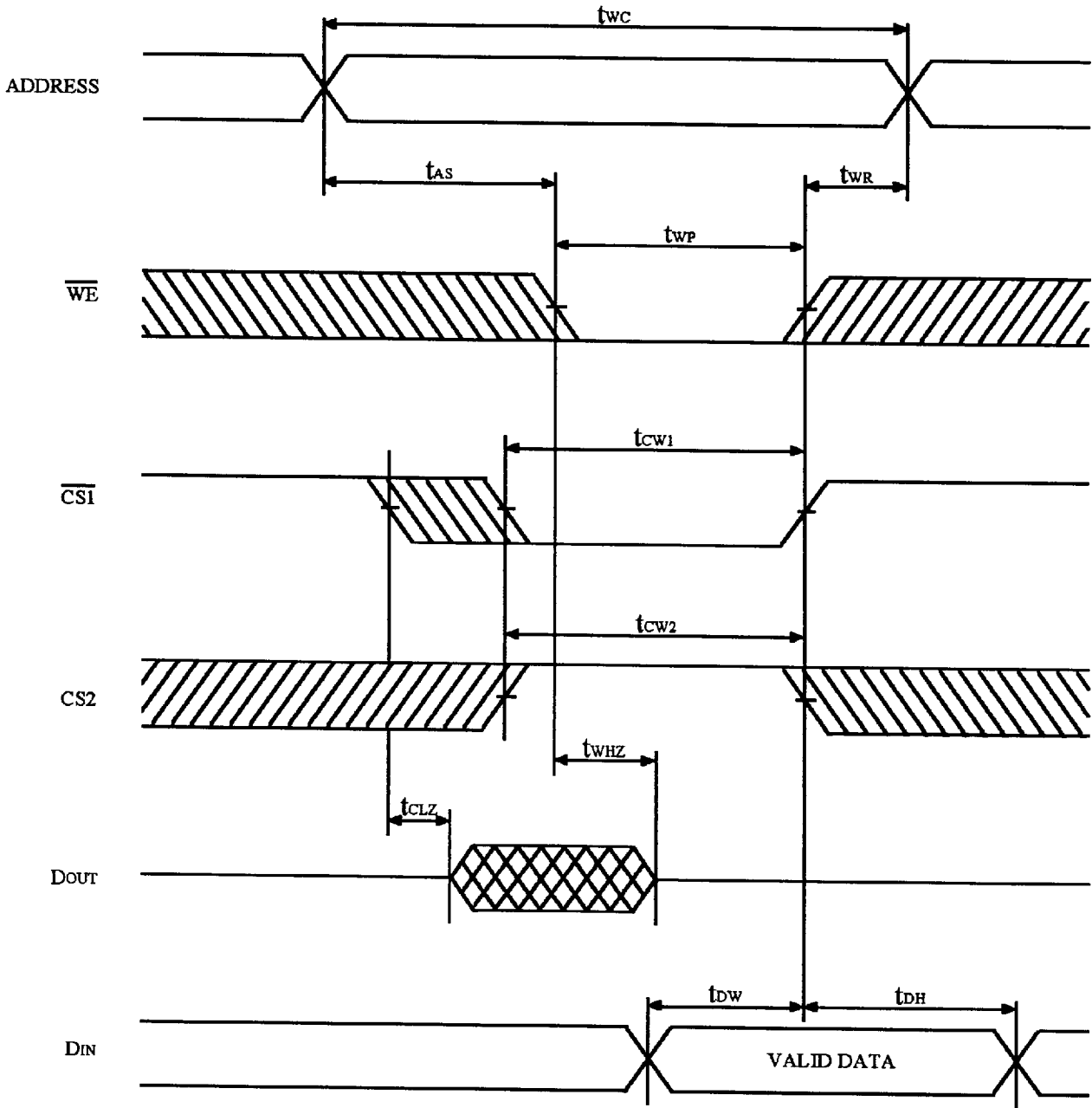
Read Cycle (Note 1)



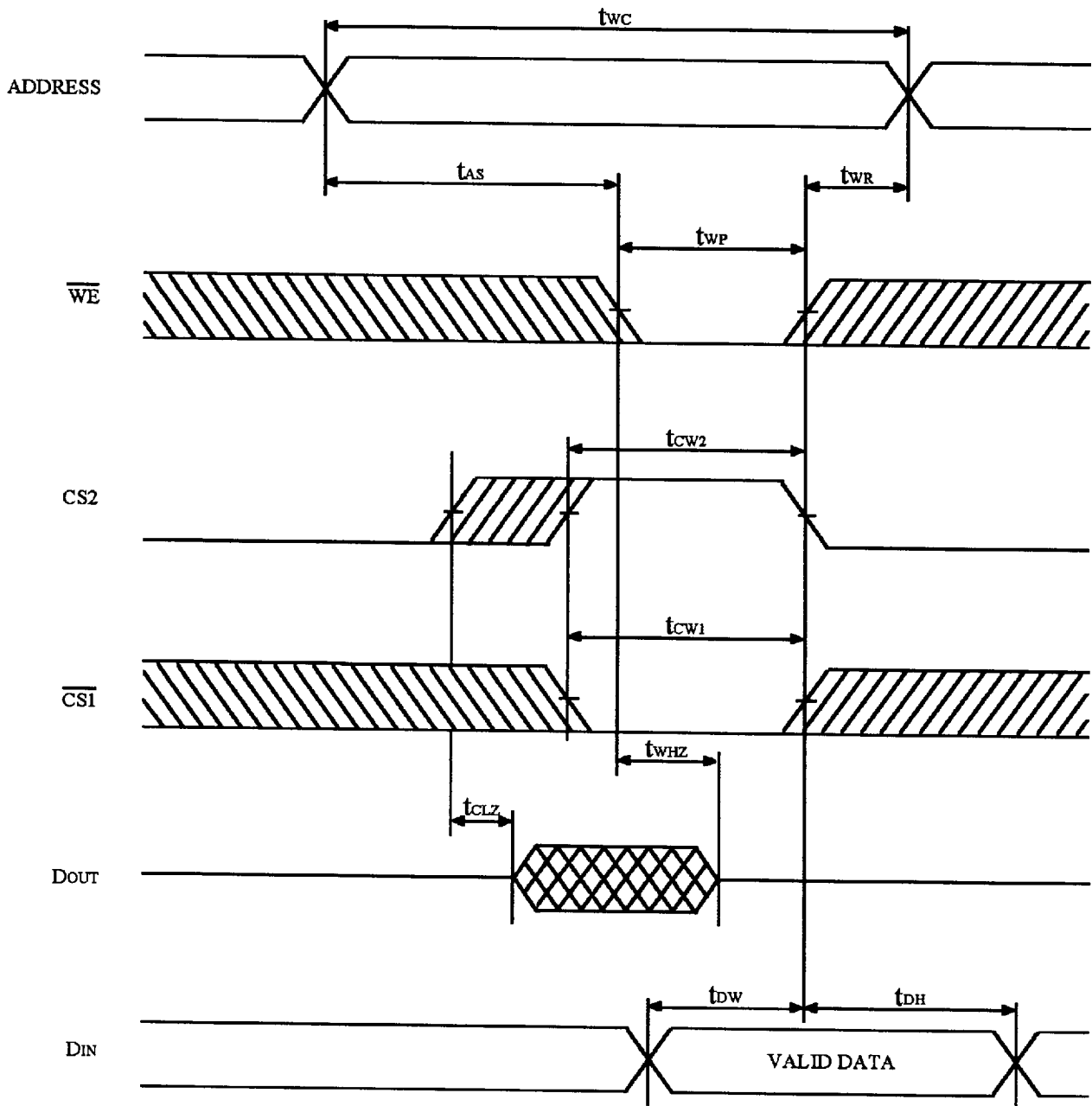
Write Cycle (1) ( $\overline{WE}$  Controlled) (Notes 2, 3, 4)



Write Cycle (2) ( $\overline{\text{CS1}}$  Controlled) (Notes 4)



**Write Cycle (3) (CS2 Controlled) (Notes 4)**



**Notes:**

1.  $\overline{WE}$  is High for Read Cycle.
2. Assuming that  $\overline{CS1}$  Low transition or CS2 High transition occurs coincident with or after  $\overline{WE}$  Low transition. Outputs remain in a high impedance state.
3. Assuming that  $\overline{CS1}$  High transition or CS2 Low transition occurs coincident with or prior to  $\overline{WE}$  High transition. Outputs remain in a high impedance state.
4. Assuming that  $\overline{OE}$  is high for write cycle. Outputs are in a high impedance state during this period.



**Capacitance (f = 1MHz, T<sub>A</sub> = 25°C)**

Symbol	Parameter	Test Conditions	Min	Max	Unit
C <sub>IN</sub>	Input Capacitance	V <sub>I</sub> = 0V	-	8	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>O</sub> = 0V	-	8	pF

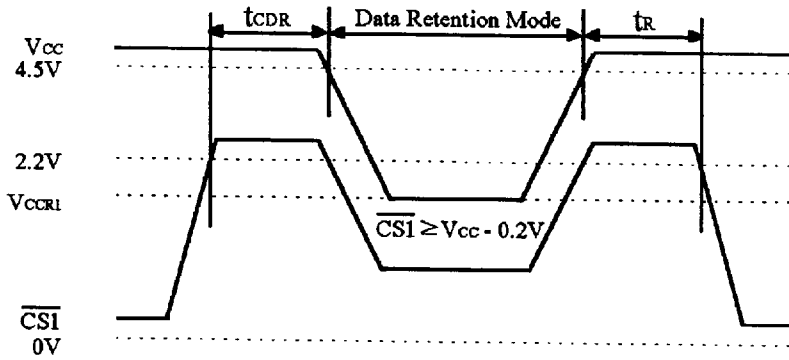
\*Note: This parameter is sampled and not 100% tested.

**Data Retention Characteristics (T<sub>A</sub> = 0 ~ 70°C)**

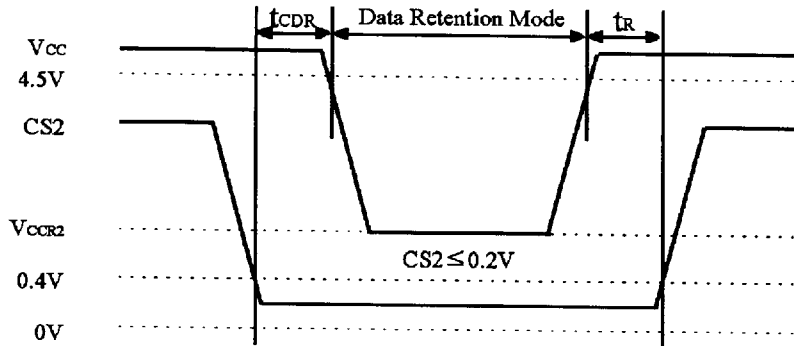
Symbol	Parameter	Min	Typ	Max	Unit	
V <sub>CCR</sub>	Data Retention Supply Voltage	2.0	-	5.5	V	
I <sub>CCR</sub>	Data Retention Current	V <sub>CC</sub> = 3.0V	L	1	50*	μA
			LL	1	25	
t <sub>CDR</sub>	Chip Select to Data Retention Time	0	-	-	ns	
t <sub>R</sub>	Operation Recovery Time	5	-	-	ns	

\*20μA max at T<sub>A</sub> = 0 ~ 40°C ...

**• Low V<sub>CC</sub> Data Retention Mode: (1)  $\overline{CS1}$  Controlled**



**• Low V<sub>CC</sub> Data Retention Mode: (2) CS2 Controlled**

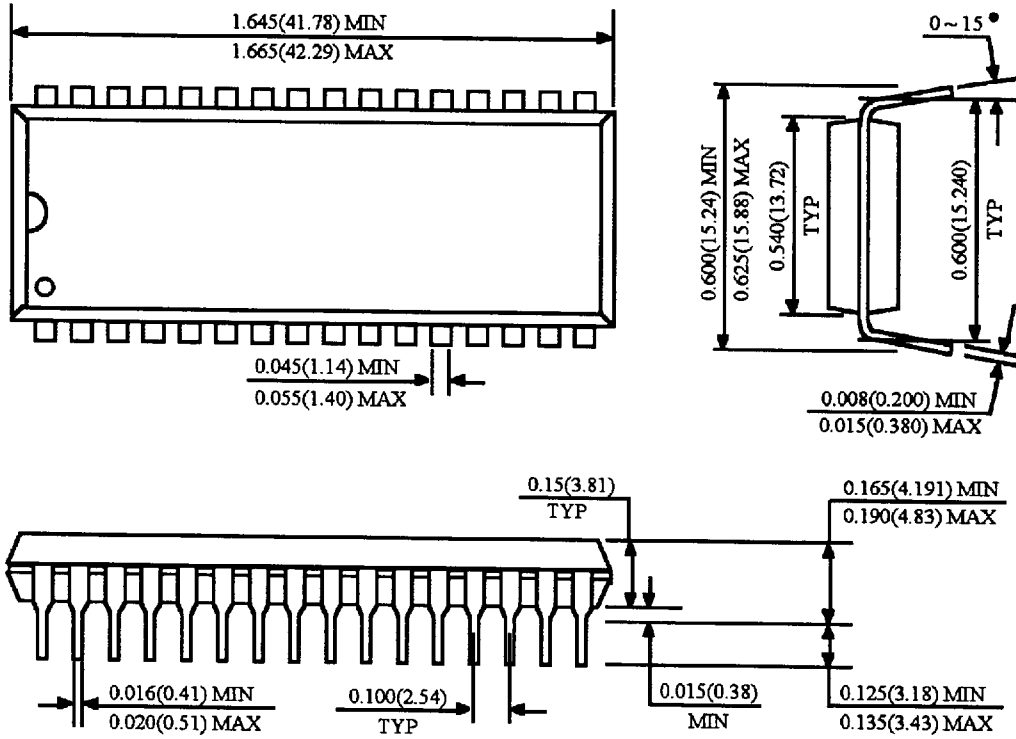


Notes: In Data Retention Mode, CS<sub>2</sub> controls the Address,  $\overline{WE}$ ,  $\overline{CS1}$ ,  $\overline{OE}$  and D<sub>IN</sub> buffer. If CS<sub>2</sub> controls data retention mode, V<sub>IN</sub> for these inputs can be in the high impedance state. If CS<sub>1</sub> controls the data retention mode, CS<sub>2</sub> must satisfy either CS<sub>2</sub> ≥ V<sub>CC</sub> - 0.2V or CS<sub>2</sub> ≤ 0.2V. The other input levels (Address,  $\overline{WE}$ ,  $\overline{OE}$ , I/O) can be in the high impedance state.

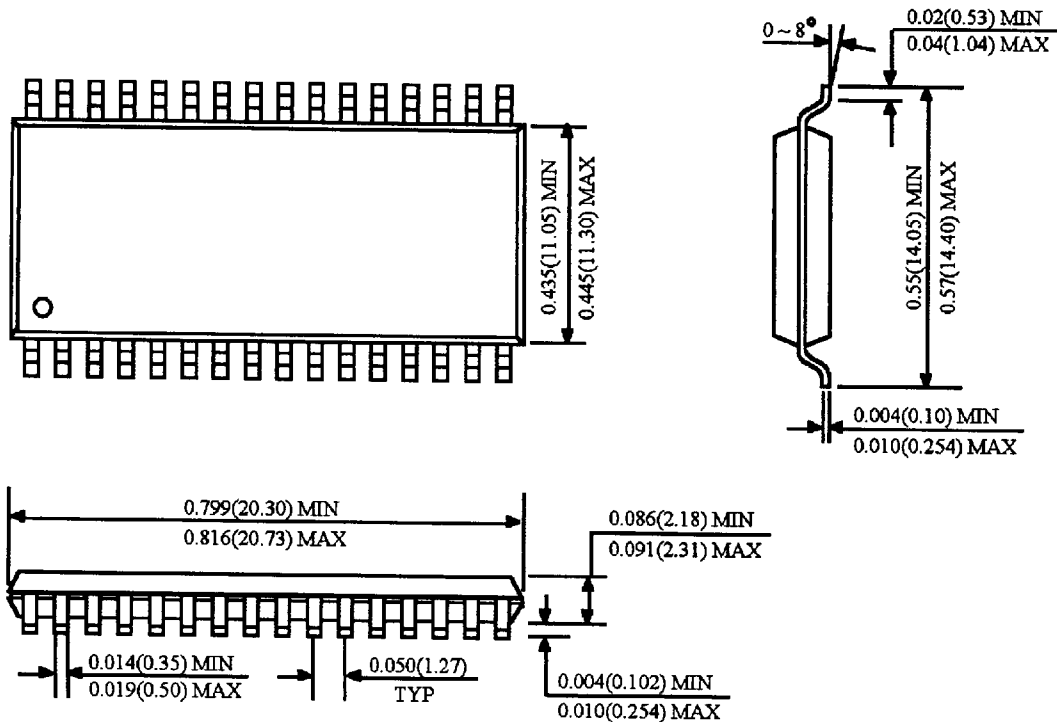
**Package Dimensions**

Unit: Inches (mm)

**32 DIP - A**



**32 SOP - A**



32 TSOP I

Unit: Inches (mm)

